

## UMF Equipment – Semi-automatic Wire Bonder System

### F&K Delvotec 5630

The wire bonder is the equipment of making interconnections (using aluminum wires with diameter of tens micrometers) between an integrated circuit (IC) or other semiconductor device and its packaging during semiconductor device fabrication. It can be used to connect an IC to other electronics or to connect from one PCB to another. It is generally considered the most cost-effective and flexible interconnect equipment, and is used to assemble the vast majority of semiconductor packages.

- Features:
- **Substrate size:** 4" work holder
  - **Speed:** Up to 30 wires / min.
  - **Bond head:** Wedge-Wedge Thin-Wire (Al), axis of rotation  $\pm 360^\circ$
  - **Ultrasonic system:** 60kHz/ 100kHz
  - **Wire size:** 25  $\mu\text{m}$
  - **Heater:** Up to 200°C
  - **Operating mode:** Single bond (manual-automatic) or multi wire (semi and fully automatic)

Please refer to supplier information page: <https://www.fkdelvotec.com/en/> for further details of the system.  
For any inquiry, please contact Dr. Terence Wong (Tel: 3400 2075; Email: [tai-lun.wong@polyu.edu.hk](mailto:tai-lun.wong@polyu.edu.hk)).



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